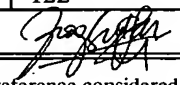
 Substitute for FORM PTO-1449 U.S. Department of Commerce Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		Application Number	10/081,074		
		Filing Date	2/12/2002		
		First Named Inventor	Sergey Lopatin		
Sheet 1 of 1		Attorney Docket No.	P1406		
U.S. PATENT DOCUMENTS					
Examiner Initial	Cite No.	U.S. Patent Document Number	Name of Patentee or Applicant of Cited Documents	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
SK	1	6,197,181 B1	Chen, Lin Lin	3/6/2001	
SK	2	6,022,808	Nogami, et al.	2/8/2000	
FOREIGN PATENT DOCUMENTS					
Examiner Initials'	Cite No.	Foreign Patent Document Office Number Code	Name of Patentee or Applicant of Cited document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appears
OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS					
Examiner Initials'	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.			
SK	1	PETER VAN ZANT, "Microchip Fabrication: A Practical Guide to Semiconductor Processing", 3 rd Ed., p. 392 and 397 (1997)			
SK	2	A. Krishnamoorthy, D. Duquette and S. Murarka, "Electrochemical Codeposition and Electrical Characterization of a Copper-Zinc Alloy Metallization", in edited by Adricacos, et al., Electrochem Society Symposium Proceedings, Vol. 99-9, May 3-6, Seattle, p. 212			
SK	3	J. Cunningham, "Using Electrochemistry to Improve Copper Interconnect", in Semiconductor International, Spring 2000 (May)			
SK	4	L. Chen and T. Ritzdorf, "ECD Seed Layer for Inlaid Copper Metallization" in edited by Andricacos, et al., Electrochem Society Proceedings, Vol. 99-9, May 3-6, Seattle, p. 122			
Examiner Signature: 			Date Considered: 4/1/03		
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.					

¹Unique citation designation number. ²See attached Kinds of U.S. Patent Documents. ³Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶Applicant is to place a check mark here if English Language Translation is attached.